



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20250218000.1**

**Qualification of RFAB as an additional Fab site option, Die Revision, Data sheet and Assembly Site (TAI)/BOM options for select devices Change Notification / Sample Request**

**Date:** February 18, 2025

**To:** Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20250218000.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TXS0108EPWR	TXS0108EPWR
TXS0108EPWRG4	TXS0108EPWR

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20250218000.1	<b>PCN Date:</b>	February 18, 2025
<b>Title:</b>	Qualification of RFAB as an additional Fab site option, Die Revision, Data sheet and Assembly Site (TAI)/BOM options for select devices		
<b>Customer Contact:</b>	Change Management Team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 19, 2025	<b>Sample requests accepted until:</b>	April 19, 2025*
*Sample requests received after April 19, 2025 will not be supported.			
<b>Change Type:</b>			
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

### PCN Details

#### Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to Assembly Site (TAI)/BOM options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FR-BIP-1	ASLC10	200mm	RFAB	LBC7	300mm

The die was also changed as a result of the process change to accommodate the change in Assembly technology

Construction differences are as follows:

	MLA	MLA (new)	TAI
Bond wire composition, diameter	Cu, 0.96mil	Cu, 0.8 mil	Cu, 0.8 mil

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



TXS0108E  
SCES642L – DECEMBER 2007 – REVISED NOVEMBER 2024

Changes from Revision K (April 2024) to Revision L (November 2024)		Page
• Added DGS package.....		1
• Updated thermal information.....		6
• Updated pulse duration and open-drain in Timing Requirements.....		8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TXS0108E	SCES642K	<b>SCES64L</b>	<a href="http://www.ti.com/product/TXS0108E">http://www.ti.com/product/TXS0108E</a>

Qual details are provided in the Qual Data Section.

#### Reason for Change:

Supply Continuity

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

### Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

#### RoHS

#### REACH

#### Green Status

#### IEC 62474

<input checked="" type="checkbox"/> No Change			
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### Changes to product identification resulting from this PCN:

#### Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

#### Die Rev:

##### Current

##### New

Die Rev [2P]	<b>Die Rev [2P]</b>
-	<b>A</b>

#### Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
<b>TI Taiwan</b>	<b>TAI</b>	<b>TWN</b>	<b>Chung Ho, New Taipei City</b>

Sample product shipping label (not actual product label):



#### Product Affected:

TXS0108EPWR	TXS0108EPWRG4
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## Qualification Report(MLA)

Approve Date 09-DECEMBER-2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TWS0108EPWR	QBS Reference: TMUX1308QPWRQ1	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74AXC8T245QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	-
ESD	E2	ESD CDM	-	2000 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-
ESD	E2	ESD HBM	-	5000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TWS0108EPWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

## Qualification Report (TAI)

Approve Date 09-DECEMBER -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TXS0108EPWR</a>	QBS Reference: <a href="#">SN3257QDYYRQ1</a>	QBS Reference: <a href="#">ADS127L11IPWR</a>	QBS Reference: <a href="#">MSP430FR2355TDBT</a>	QBS Reference: <a href="#">TXS0108ERKSR</a>	QBS Reference: <a href="#">TXS0108EPWR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	Per QSS-009-018	1 Step	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TXS0108EPWR</a>	QBS Reference: <a href="#">SN3257QDYYRQ1</a>	QBS Reference: <a href="#">ADS127L11IPWR</a>	QBS Reference: <a href="#">MSP430FR2355TDBT</a>	QBS Reference: <a href="#">TXS0108ERKSR</a>	QBS Reference: <a href="#">TXS0108EPWR</a>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	1/22/0	1/22/0	1/22/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	1/5/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/3/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-	-
FTY	E6	Final Test Yield	-	-	-	-	1/1/0	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TXS0108EPWR is qualified at MSL1 260C

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The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

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